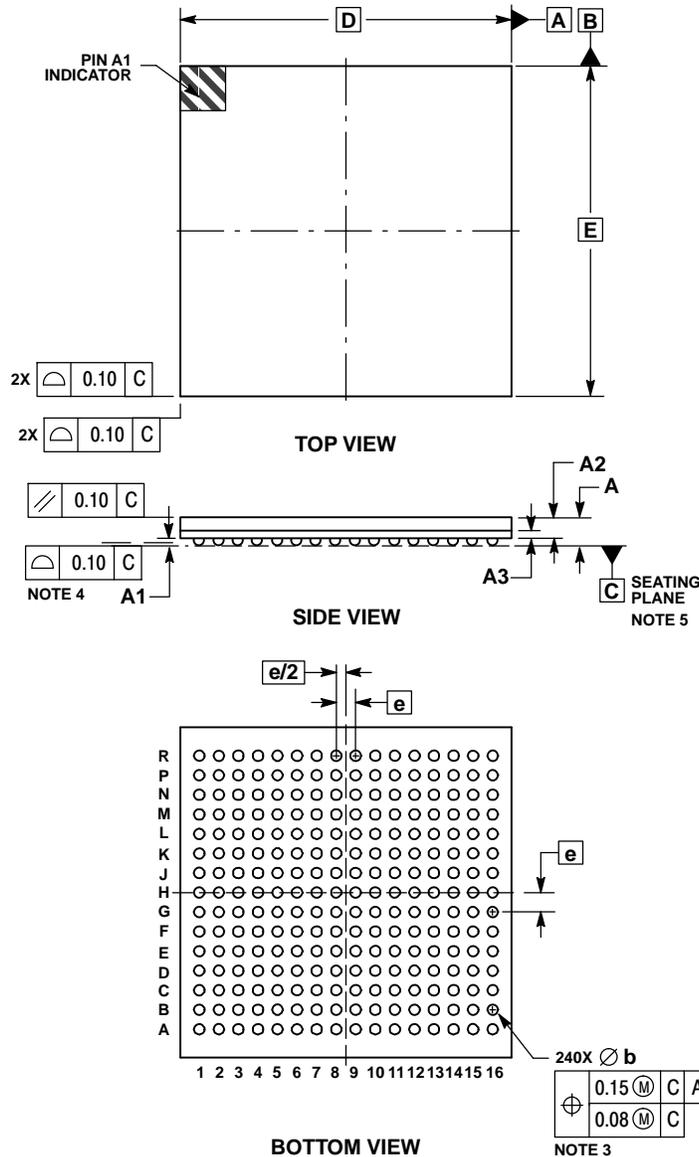**LFBGA240, 11x11**
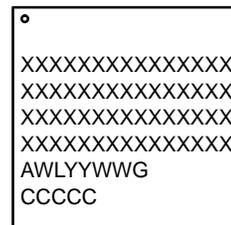CASE 566EY
ISSUE O

DATE 05 NOV 2014

SCALE 1:1

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	–––	1.31
A1	0.20	0.30
A2	0.70 REF	
A3	0.26 REF	
b	0.30	0.40
D	11.00 BSC	
E	11.00 BSC	
e	0.65 BSC	

PIN A1 INDICATOR

2X ⌒ 0.10 C

2X ⌒ 0.10 C

TOP VIEW

∥ 0.10 C

⌒ 0.10 C

NOTE 4 A1

SIDE VIEW

A2
A
A3

C SEATING PLANE
NOTE 5

e/2
e

R P N M L K J H G F E D C B A

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16

BOTTOM VIEW

240X ⌀ b

⊕	0.15 Ⓜ C A B
	0.08 Ⓜ C

NOTE 3

GENERIC MARKING DIAGRAM*

```
○
XXXXXXXXXXXXXX
XXXXXXXXXXXXXX
XXXXXXXXXXXXXX
XXXXXXXXXXXXXX
AWLYYWWG
CCCCC
```
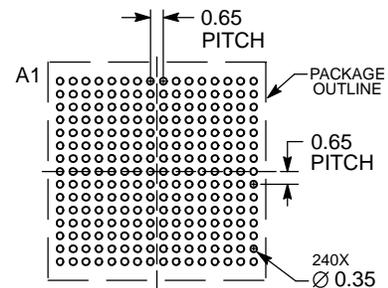
A   = Assembly Location
WL   = Wafer Lot
YY   = Year
WW   = Work Week
G   = Pb–Free Package
CC   = Country of Origin

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*

0.65 PITCH

A1

PACKAGE OUTLINE

0.65 PITCH

240X ⌀ 0.35

DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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